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January 30, 2002

Date

**Andrew Romero** 

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Signature

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of:

Applicant:

Dong-Hyuk Ju et al.

Serial No:

09/879,724

Filing Date: June 12, 2001

**Art Unit:** 

2826

Examiner:

Ahmed N. Sefer

Title: LEAKY, THERMALLY CONDUCTIVE INSULATOR MATERIAL (LTCIM) IN

SEMICONDUCTOR-ON-INSULATOR (SOI) STRUCTURE

**Commissioner for Patents** U.S. Patent and Trademark Office Washington, D.C. 20231

## **REPLY TO OFFICE ACTION DATED JANUARY 22, 2002**

Dear Sir:

This paper is responsive to the written restriction requirement dated January 22, 2002.